



Gallium Nitride 50V, 500W, 3.4-3.8GHz RF Power Transistor

Description

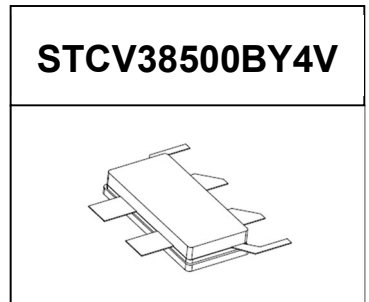
The STCV38500BY4V is a 500-watt, internally matched GaN HEMT, designed for 5G cellular applications with frequencies from 3.4-3.8GHz, **enabled by wide band VBW capability to support IBW ≥ 200MHz.**

It can be configured as asymmetrical Doherty for 4G or 5G application, delivering 55 to 70W average power, according to normal 8 to 9dB back off.

There is no guarantee of performance when this part is used in applications designed Outside of these frequencies.

- Typical Doherty Pulsed CW and 1C W--CDMA Characterization Performance:

3.4-3.8GHz full band Doherty $V_{DD} = 48$ Vdc, $I_{DQA} = 280$ mA, $V_{GSB} = -6$ Vdc,



Freq (GHz)	Pulse CW Signal(1)			Pavg=47.5dBm WCDMA Signal(2)			Pavg=48.5dBm WCDMA Signal(2)		
	P1dB Gain (dB)	Psat (dBm)	Psat (W)	Gp (dB)	Eff(%)	ACPR5M (dBc)	Gp (dB)	Eff(%)	ACPR5M (dBc)
3.4	11.55	56.54	450	12.09	45.47	-27.63	11.91	47.66	-27.75
3.5	12.16	56.73	471	12.35	46.32	-28.85	12.17	48.07	-28.90
3.6	12.78	56.85	484	12.62	46.05	-32.58	12.44	47.69	-32.71
3.7	12.49	56.80	479	12.55	44.82	-34.39	12.35	46.74	-34.03
3.8	12.22	56.44	440	12.04	43.06	-36.84	11.84	45.09	-35.56

3.4-3.6GHz full band Doherty $V_{DD} = 46$ Vdc, $I_{DQA} = 260$ mA, $V_{GSB} = -6$ Vdc,

Freq (GHz)	Pulse CW Signal(1)			Pavg=47.5dBm WCDMA Signal(2)			Pavg=48.5dBm WCDMA Signal(2)		
	P1dB Gain (dB)	Psat (dBm)	Psat (W)	Gp (dB)	Eff(%)	ACPR5M (dBc)	Gp (dB)	Eff(%)	ACPR5M (dBc)
3.4	12.52	56.44	440	12.18	48.88	-28.35	11.90	51.10	-28.54
3.5	12.60	56.27	423	12.06	49.75	-29.56	11.81	51.84	-29.91
3.6	12.33	56.11	408	11.66	49.20	-32.08	11.48	51.43	-32.30

Notes:

(1) Pulse Width=100 us, Duty cycle=20%

(2) WCDMA signal: 3GPP test model 1; 1 to 64 DPCH; Channel Bandwidth=3.84MHz, PAR =10.5 dB at 0.01 % probability on CCDF.

Recommended driver: Class AB 1 stages discrete: STBV38081C6

Applications

- Asymmetrical Doherty amplifier within N78/N77 5G band and B42 4G band
- S band power amplifier

Important Note: Proper Biasing Sequence for GaN HEMT Transistors

Turning the device ON

1. Set VGS to the pinch-off (VP) voltage, typically -5 V
2. Turn on VDS to nominal supply voltage
3. Increase VGS until IDS current is attained
4. Apply RF input power to desired level

Turning the device OFF

1. Turn RF power off
2. Reduce VGS down to VP, typically -5 V
3. Reduce VDS down to 0 V
4. Turn off VGS

Figure 1: Pin Connection definition

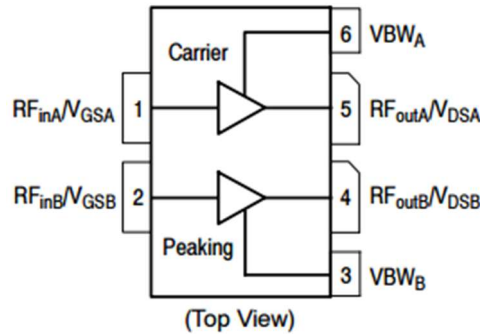


Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain--Source Voltage	V_{DSS}	+200	Vdc
Gate--Source Voltage	V_{GS}	-8 to +0.5	Vdc
Operating Voltage	V_{DD}	55	Vdc
Maximum gate current	I_{GS}	22.4	mA
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature	T_C	+150	°C
Operating Junction Temperature	T_J	+225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case by FEA $T_C = 85^\circ\text{C}$, $P_{out} = 70\text{W}$, 3.6GHz Doherty application board	$R_{\theta JC}$	1.25	°C /W

Table 3. Electrical Characteristics (TA = 25°C unless otherwise noted)

DC Characteristics (main path, measured on wafer prior to packaging)

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8\text{V}$; $I_{DS} = 21.6\text{mA}$	V_{DSS}		200		V
Gate Threshold Voltage	$V_{DS} = 10\text{V}$, $I_D = 21.6\text{mA}$	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	$V_{DS} = 50\text{V}$, $I_{DS} = 100\text{mA}$, Measured in Functional Test	$V_{GS(Q)}$		-3		V

DC Characteristics (peak path, measured on wafer prior to packaging)

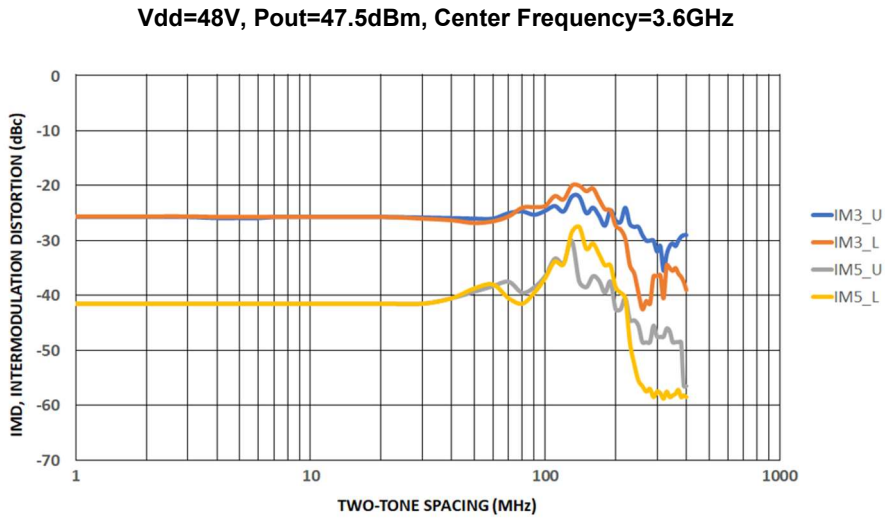
Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Drain-Source Breakdown Voltage	$V_{GS} = -8\text{V}$; $I_{DS} = 34\text{mA}$	V_{DSS}		200		V
Gate Threshold Voltage	$V_{DS} = 10\text{V}$, $I_D = 34\text{mA}$	$V_{GS(th)}$	-4		-2	V
Gate Quiescent Voltage	$V_{DS} = 50\text{V}$, $I_{DS} = 220\text{mA}$, Measured in Functional Test	$V_{GS(Q)}$		-3.15		V

Ruggedness Characteristics

Characteristic	Conditions	Symbol	Min	Typ	Max	Unit
Load mismatch capability	3.6GHz, $P_{out} = 70\text{W}$ WCDMA 1 Carrier in Doherty circuit All phase, No device damages	VSWR		10:1		



Figure 2: Intermodulation Distortion Products versus Two-Tone Spacing



3.4-3.8GHz full band tuning

Figure 3: Efficiency and power gain as function of Pout (3.4-3.8GHz Doherty)

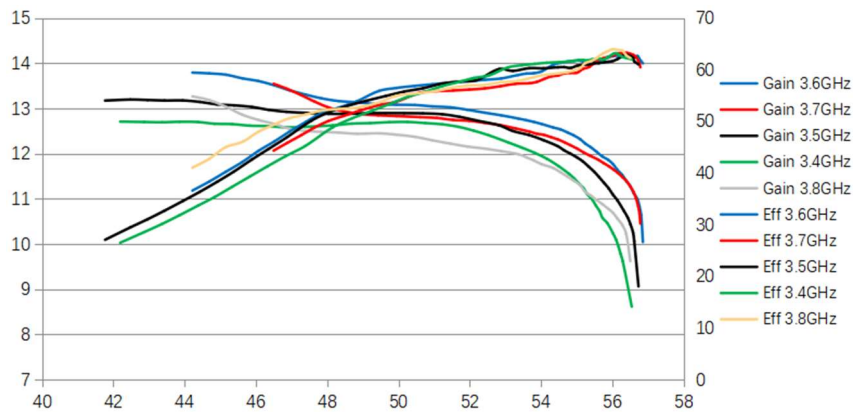


Figure 4: Network analyzer output, S11 and S21 (3.4-3.8GHz Doherty)

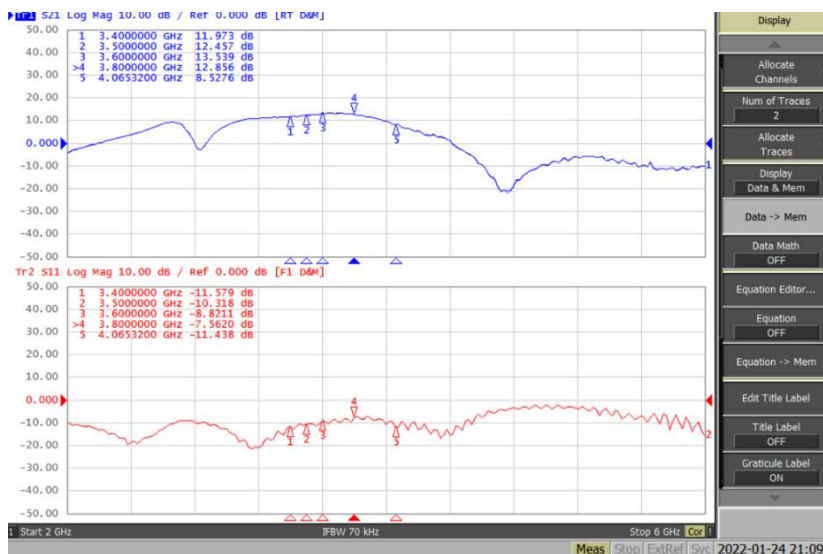


Figure 5: Picture of application board Doherty circuit for 3.4-3.8GHz

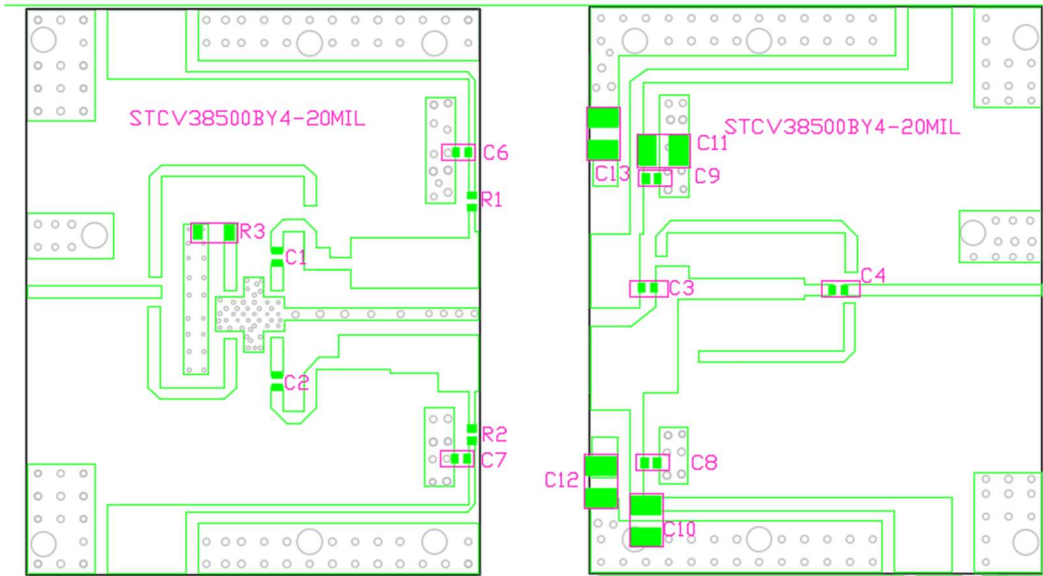


Table 4. Bill of materials of application board (PCB layout upon request, RO4350B 20mils)

Part	Quantity	Description	Part Number	Manufacture
C1,C2,C6,C4 C7,C8,C9	7	8.2pF High Q Capacitor	251SHS8R2BSE	TEMEX
C3	1	2.0pF High Q Capacitor	ATC600S2R0	ATC
C10,C11,C12,C13	4	10uF MLCC	RS80R2A106M	MARUWA
R1,R2	2	10 Ω Power Resistor	ESR03EZPF100	ROHM
R3	1	51 Ω Power Resistor	S1206N	RN2
COU1	1	3 dB Bridge	XC3500P-03S	ANAREN
T1	1	500W GaN Dual Transistor	STCV38500BY4V	Innogrations

3.4-3.6GHz full band tuning

Figure 3: Efficiency and power gain as function of Pout (3.4-3.6GHz Doherty)

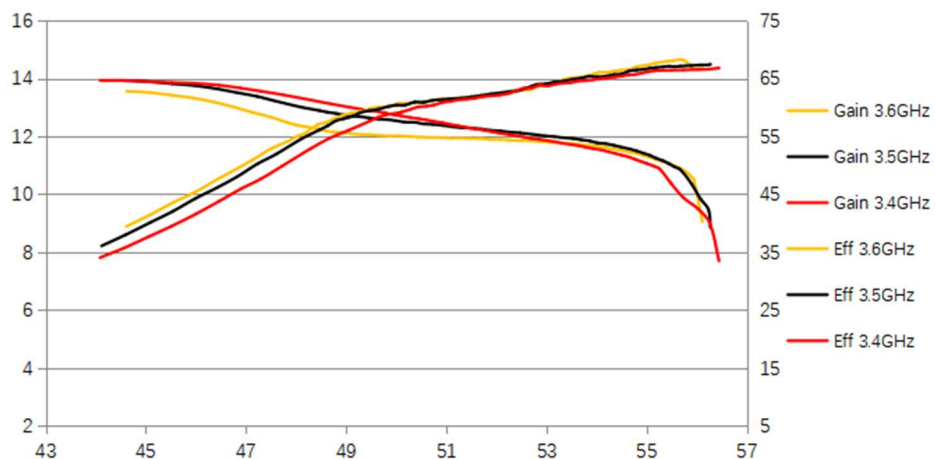


Figure 4: Network analyzer output, S11 and S21 (3.4-3.6GHz Doherty)

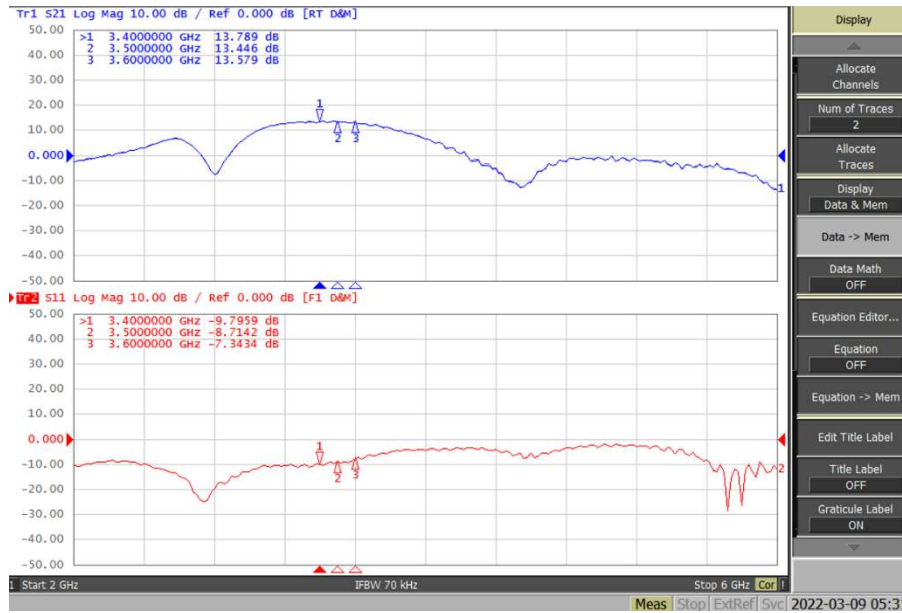


Figure 5: Picture of application board Doherty circuit for 3.4-3.6GHz

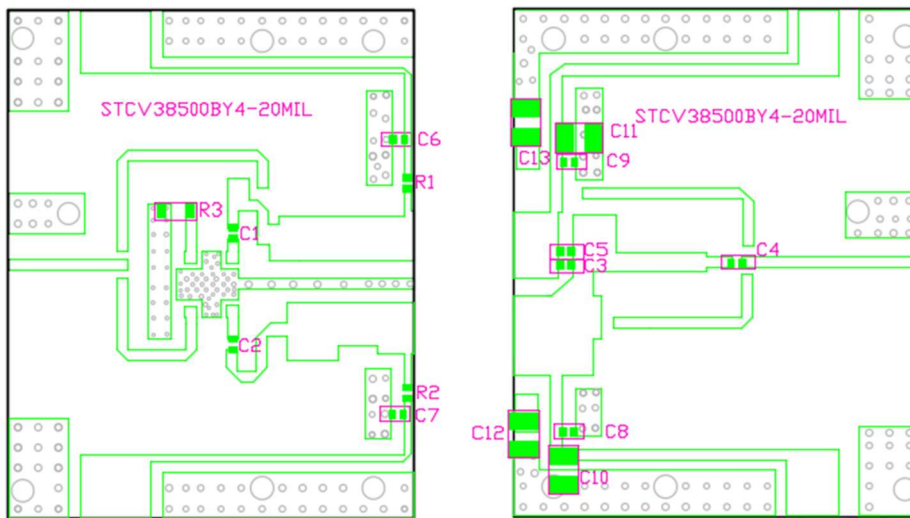
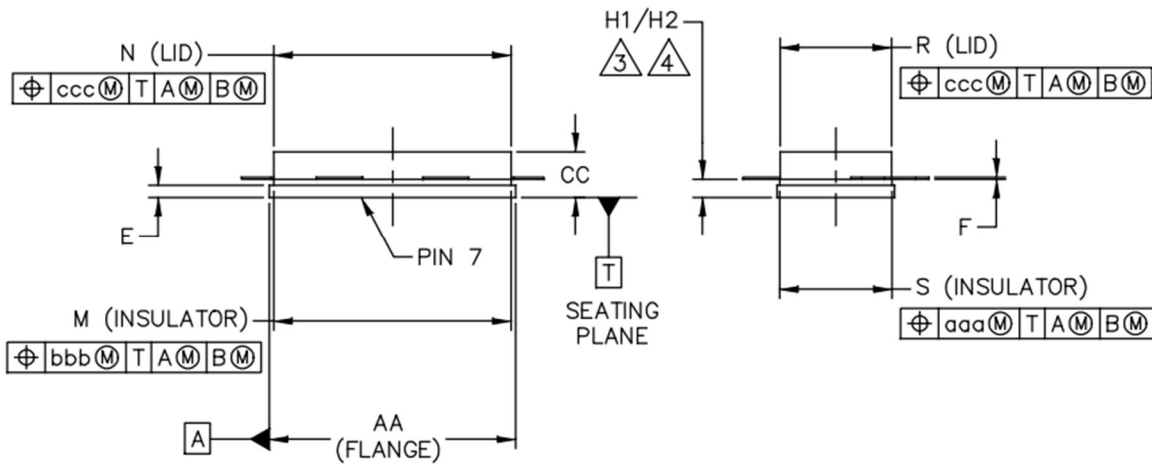
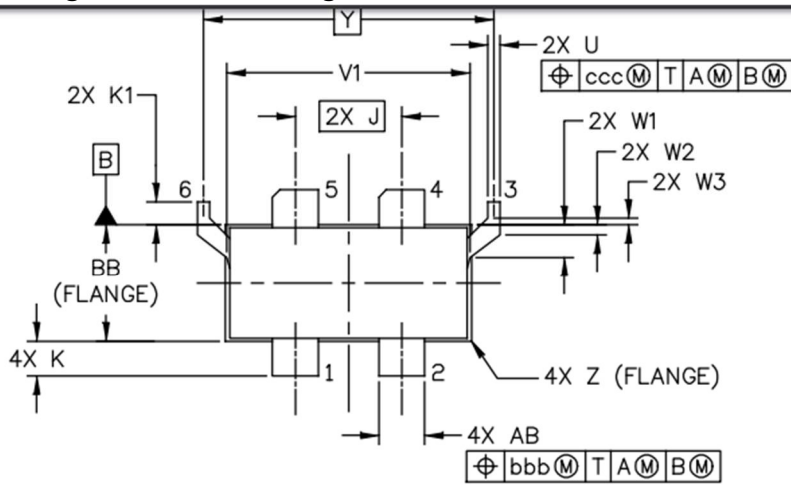


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Part	Quantity	Description	Part Number	Manufacture
C1,C2,C6,C4 C7,C8,C9	7	8.2pF High Q Capacitor	251SHS8R2BSE	TEMEX
C3,C5	2	1.8pF High Q Capacitor	ATC600S1R8	ATC
C10,C11,C12,C13	4	10uF MLCC	RS80R2A106M	MARUWA
R1,R2	2	10 Ω Power Resistor	ESR03EZPF100	ROHM
R3	1	51 Ω Power Resistor	S1206N	RN2
COU1	1	3 dB Hybrid	XC3500P-03S	ANAREN
T1	1	500W GaN Dual Transistor	STCV38500BY4V	Innegration



Earless Flanged Ceramic Package; 6 leads- BY4V



DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	R	.365	.375	9.27	9.53
BB	.380	.390	9.65	9.91	S	.365	.375	9.27	9.53
CC	.125	.170	3.18	4.32	U	.035	.045	0.89	1.14
E	.035	.045	0.89	1.14	V1	.795	.805	20.19	20.45
F	.004	.007	0.10	0.18	W1	.0975	.1175	2.48	2.98
H1	.057	.067	1.45	1.70	W2	.0225	.0425	0.57	1.08
H2	.054	.070	1.37	1.78	W3	.0125	.0325	0.32	0.83
J	.350 BSC		8.89 BSC		Y	.956 BSC		24.28 BSC	
K	.0995	.1295	2.53	3.29	Z	R.000	R.040	R0.00	R1.02
K1	.070	.090	1.78	2.29	AB	.145	.155	3.68	3.94
M	.774	.786	19.66	19.96	aaa	.005		0.13	
N	.772	.788	19.61	20.02	bbb	.010		0.25	
					ccc	.015		0.38	



Revision history

Table 4. Document revision history

Date	Revision	Datasheet Status
2022/1/25	V1.0	Preliminary Datasheet Creation
2022/3/10	V1.1	Add 3.4-3.6GHz narrower band app data

Application data based on LWH-22-04/09

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